

SID

Factory: Rot am See

Article:

573

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

17.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	B00
A-RS-FR4-Prepreg-106-TG150-HF	50200640	85		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
B-RS-FR4-ML-0.15mm-070+070-TG150-HF	50200979	70	L2	4	
		150			
		70	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	160		5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6	
B-RS-FR4-ML-0.15mm-070+070-TG150-HF	50200979	70	L4	7	
		150			
		70	L5		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	160		8	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		9	
B-RS-FR4-ML-0.15mm-070+070-TG150-HF	50200979	70	L6	10	
		150			
		70	L7		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	85		11	
A-RS-FR4-Prepreg-106-TG150-HF	50200640	0		12	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	13	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1430 µm

Version 1.2.14.15

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